

## ICL3224, ICL3226, ICL3238

1μA, +3V to +5.5V, 250kbps, RS-232 Transceivers with Enhanced Automatic Powerdown

The ICL3224, ICL3226, and ICL3238 (ICL32xx) devices are 3.0V to 5.5V powered RS-232 transmitters/receivers that meet EIA/TIA-232 and V.28/V.24 specifications, even at  $V_{CC} = 3.0V$ . Targeted applications are PDAs, Palmtops, and notebook and laptop computers where low operational power consumption and even lower standby power consumption are critical. Efficient on-chip charge pumps, coupled with manual and enhanced automatic powerdown functions, reduce the standby supply current to a 1µA trickle. Small footprint packaging, and the use of small, low value capacitors ensure board space savings. Data rates greater than 250kbps are ensured at worst case load conditions. This family is fully compatible with 3.3V only systems, mixed 3.3V and 5.0V systems, and 5.0V only systems.

The ICL3238 is a 5 driver, 3 receiver device that includes a noninverting always-active receiver for Ring Indicator monitoring.

The ICL32xx devices feature an enhanced automatic powerdown function that powers down the on-chip power supply and driver circuits. Powerdown occurs when all receiver and transmitter inputs detect no signal transitions for a period of 30s. These devices power back up automatically whenever they sense a transition on any transmitter or receiver input.

<u>Table 1</u> summarizes the features of the devices represented by this datasheet, and <u>AN9863</u> summarizes the features of each device in the ICL32xx 3V family.

#### **Related Literature**

For a full list of related documents, visit our website:

ICL3224, ICL3226, and ICL3238 device pages

#### **Features**

- Pb-free (RoHS compliant)
- ±15kV ESD protected (human body model)
- Manual and enhanced automatic powerdown features
- Drop in replacements for MAX3224, MAX3226, MAX3238
- Meets EIA/TIA-232 and V.28/V.24 specifications at 3V
- · Latch-up free
- RS-232 compatible with V<sub>CC</sub> = 2.7V
- On-chip voltage converters require only four external 0.1µF capacitors
- Flow-through pinout (ICL3238)
- "Ready to transmit" indicator output (ICL3224/26)
- · Receiver hysteresis for improved noise immunity
- · Ensured minimum data rate: 250kbps
- Ensured minimum slew rate: 6V/µs
- Wide power supply range: Single +3V to +5.5V
- Low supply current in powerdown state: 1µA

#### **Applications**

- · Any system requiring RS-232 communication ports
  - Battery powered, hand-held, and portable equipment
  - o Laptop computers, Notebooks, Palmtops
  - o Modems, printers and other peripherals
  - o Digital cameras
  - o Cellular/mobile phones
  - Data cradles

Table 1. Summary of Features

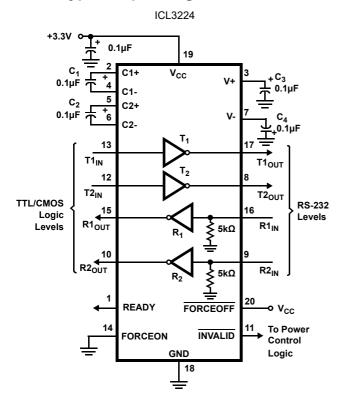
Part Number	Number of Tx.	Number of Rx.	Number of Monitor Rx. (R <sub>OUTB</sub> )	Data Rate (kbps)	Rx. Enable Function?	READY Output?	Manual Powerdown?	Enhanced Automatic Powerdown
ICL3224	2	2	0	250	No	Yes	Yes	Yes
ICL3226	1	1	0	250	No	Yes	Yes	Yes
ICL3238	5	3	1	250	No	No	Yes	Yes

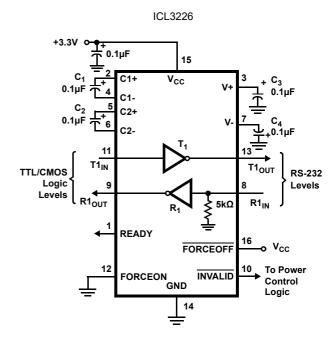
# **Contents**

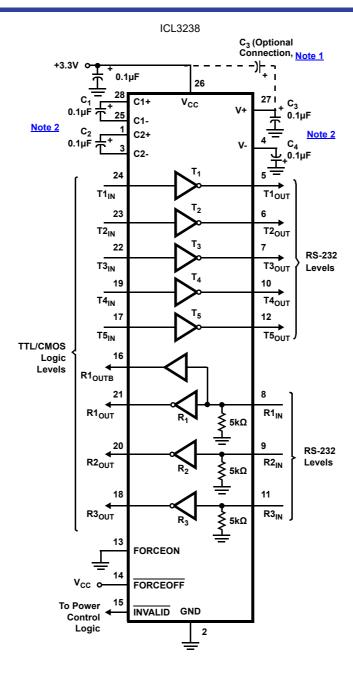
1.	Overview	. 3
1.1	Typical Operating Circuits	. 3
1.2	Ordering Information	. 4
1.3	Pin Configurations	
1.4	Pin Descriptions	. 6
2.	Specifications	. 7
2.1	Absolute Maximum Ratings	
2.2	Thermal Information	
2.3	Recommended Operating Conditions	
2.4	Electrical Specifications	
^		
	Typical Performance Curves	
4.	Application Information	
4.1	Charge-Pump	12
	1.1 Charge Pump Absolute Maximum Ratings	
4.2	Transmitters	13
4.3	Receivers	14
4.4	Powerdown Functionality	15
4.4	4.1 Software Controlled (Manual) Powerdown	16
4.4	4.2 TNVALID Output	17
4.5	Enhanced Automatic Powerdown	
4.	5.1 Emulating Standard Automatic Powerdown	18
4.	5.2 Hybrid Automatic Powerdown Options	19
4.6	READY Output (ICL3224 and ICL3226 only)	19
4.7	Capacitor Selection	19
4.8	Power Supply Decoupling	19
4.9	Transmitter Outputs when Exiting Powerdown	20
4.10	Operation Down to 2.7V	20
4.11	High Data Rates	20
4.12	Interconnection with 3V and 5V Logic	21
5.	Die Characteristics	22
6.	Revision History	23
7.	Package Outline Drawings	24

# 1. Overview

# 1.1 Typical Operating Circuits







#### Notes:

- 1. The negative terminal of C3 can be connected to either VCC or GND.
- 2. For  $V_{CC}$  = 3.15V (3.3V -5%), Use  $C_1$   $C_4$  = 0.1 $\mu$ F or greater. For  $V_{CC}$  = 3.0V (3.3V -10%), Use  $C_1$   $C_4$  = 0.22 $\mu$ F.

# 1.2 Ordering Information

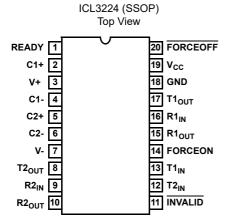
Part Number ( <u>Notes 4, 5)</u>	Part Marking	Temp. Range (°C)	Tape and Reel (Units) (Notes 3)	Package (RoHS Compliant)	Pkg. Dwg.#
ICL3226IAZ	ICL3226IAZ	-40 to 85	-	16 Ld SSOP	M16.209
ICL3226IAZ-T	ICL3226IAZ	-40 to 85	1k	16 Ld SSOP	M16.209
ICL3224CAZ (No longer available, recommended replacement: ICL3224EIAZ)	3224CAZ	0 to 70	-	20 Ld SSOP	M20.209
ICL3224CAZ-T (No longer available, recommended replacement: ICL3224EIAZ-T)	3224CAZ	0 to 70	1k	20 Ld SSOP	M20.209

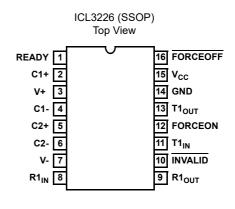
Part Number ( <u>Notes 4, 5</u> )	Part Marking	Temp. Range (°C)	Tape and Reel (Units) ( <u>Notes 3</u> )	Package (RoHS Compliant)	Pkg. Dwg.#
ICL3224IAZ (No longer available, recommended replacement: ICL3224EIAZ)	3224IAZ	-40 to 85	-	20 Ld SSOP	M20.209
ICL3224IAZ-T (No longer available, recommended replacement: ICL3224EIAZ-T)	3224IAZ	-40 to 85	1k	20 Ld SSOP	M20.209
ICL3226CAZ (No longer available, recommended replacement: ICL3226EIAZ)	ICL3226CAZ	0 to 70	-	16 Ld SSOP	M16.209
ICL3226CAZ-T (No longer available, recommended replacement: ICL3226EIAZ-T)	ICL3226CAZ	0 to 70	1k	16 Ld SSOP	M16.209
ICL3238CAZ (No longer available, recommended replacement: ICL3238EIAZ)	ICL3238CAZ	0 to 70	-	28 Ld SSOP	M28.209
ICL3238CAZ-T (No longer available, recommended replacement: ICL3238EIAZ-T)	ICL3238CAZ	0 to 70	1k	28 Ld SSOP	M28.209
ICL3238IAZ (No longer available, recommended replacement: ICL3238EIAZ)	ICL3238IAZ	-40 to 85	-	28 Ld SSOP	M28.209
ICL3238IAZ-T (No longer available, recommended replacement: ICL3238EIAZ-T)	ICL3238IAZ	-40 to 85	1k	28 Ld SSOP	M28.209

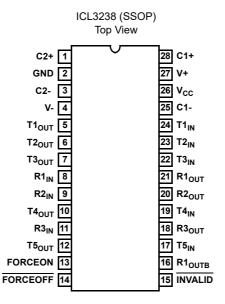
#### Notes:

- 3. See <u>TB347</u> for details about reel specifications.
- 4. Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J-STD-020.
- 5. For Moisture Sensitivity Level (MSL), see the ICL3224, ICL3226, and ICL3238 device pages. For more information about MSL, see TB363.

## 1.3 Pin Configurations







# 1.4 Pin Descriptions

Pin	Function
V <sub>CC</sub>	System power supply input (3.0V to 5.5V).
V+	Internally generated positive transmitter supply (+5.5V).
V-	Internally generated negative transmitter supply (-5.5V).
GND	Ground connection.
C1+	External capacitor (voltage doubler) is connected to this lead.
C1-	External capacitor (voltage doubler) is connected to this lead.
C2+	External capacitor (voltage inverter) is connected to this lead.
C2-	External capacitor (voltage inverter) is connected to this lead.
Tx <sub>IN</sub>	TTL/CMOS compatible transmitter Inputs.
Tx <sub>OUT</sub>	RS-232 level (nominally ±5.5V) transmitter outputs.
Rx <sub>IN</sub>	RS-232 compatible receiver inputs.
Rx <sub>OUT</sub>	TTL/CMOS level receiver outputs.
Rx <sub>OUTB</sub>	TTL/CMOS level, noninverting, always enabled receiver outputs.
INVALID	Active low output that indicates if no valid RS-232 levels are present on any receiver input.
READY	Active high output that indicates when the ICL32xx is ready to transmit (V- ≤ -4V)
FORCEOFF	Active low to shut down transmitters and on-chip power supply, which overrides any automatic circuitry and FORCEON (see <u>Table 5 on page 15</u> ).
FORCEON	Active high input to override automatic powerdown circuitry and keeps transmitters active. (FORCEOFF must be high).

# 2. Specifications

# 2.1 Absolute Maximum Ratings

Parameter	Minimum	Maximum	Unit	
V <sub>CC</sub> to Ground	-0.3	6	V	
V+ to Ground	-0.3	7	V	
V- to Ground	+0.3	-7	V	
V+ to V-		14	V	
Input Voltages				
T <sub>IN</sub> , FORCEOFF, FORCEON	-0.3	6	V	
R <sub>IN</sub>		±25	V	
Output Voltages				
T <sub>OUT</sub>		±13.2	V	
R <sub>OUT</sub> , INVALID, READY	-0.3	V <sub>CC</sub> +0.3	V	
Short-Circuit Duration				
Т <sub>ОИТ</sub>	Continuous			
ESD Rating	Se	e <u>"ESD Performance" on page</u>	9	

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

#### 2.2 Thermal Information

Thermal Resistance (Typical, Note 6)	θ <sub>JA</sub> (°C/W)
16 Ld SSOP Package	140
20 Ld SSOP Package	125
28 Ld SSOP Package	100

Notes:

<sup>6.</sup>  $\theta_{JA}$  is measured with the component mounted on a low-effective thermal conductivity test board in free air. See <u>TB379</u>.

Parameter	Minimum	Maximum	Unit
Maximum Junction Temperature (Plastic Package)		+150	°C
Maximum Storage Temperature Range	-65	+150	°C
Pb-Free Reflow Profile		see <u>TB493</u>	

# 2.3 Recommended Operating Conditions

Parameter	Minimum	Maximum	Unit
Temperature Range			
ICL32xxC	0	+70	°C
ICL32xxI	-40	+85	°C

# 2.4 Electrical Specifications

Test conditions:  $V_{CC}$  = 3V to 5.5V,  $C_1$  -  $C_4$  = 0.1 $\mu$ F (ICL3238:  $C_1$  -  $C_4$  = 0.22 $\mu$ F at VCC = 3V); unless otherwise specified. Typical values are at TA = 25°C

Parameter	Test Conditions		Temp (°C)	Min	Тур	Max	Unit
DC Characteristics			•	•	•		
Supply Current, Automatic Powerdown	All $R_{IN}$ open, FORCEON = GND, $\overline{FORCEOFF} = V_{CC}$		25	-	1.0	10	μA
Supply Current, Powerdown	FORCEOFF = GND		25	-	1.0	10	μΑ
Supply Current, Automatic Powerdown Disabled	All outputs unloaded, FORCEO V <sub>CC</sub> = 3.15V	N = FORCEOFF = V <sub>CC</sub>	25	-	0.3	1.0	mA
Logic and Transmitter Inputs and	d Receiver Outputs						
Input Logic Threshold Low	T <sub>IN</sub> , FORCEON, FORCEOFF		Full	-	-	8.0	V
Input Logic Threshold High	T <sub>IN</sub> , FORCEON, FORCEOFF V <sub>CC</sub> = 3.3V		Full	2.0	-	-	V
	V <sub>CC</sub> = 5.0V		Full	2.4	-	-	V
Transmitter Input Hysteresis			25	-	0.5	-	V
Input Leakage Current	T <sub>IN</sub> , FORCEON, FORCEOFF		Full	-	±0.01	±1.0	μΑ
Output Leakage Current	FORCEOFF = GND		Full	-	±0.05	±10	μΑ
Output Voltage Low	I <sub>OUT</sub> = 1.6mA		Full	-	-	0.4	V
Output Voltage High	I <sub>OUT</sub> = -1.0mA		Full	V <sub>CC</sub> -0.6	V <sub>CC</sub> -0.1	-	V
Receiver Inputs							
Input Voltage Range			Full	-25	-	25	V
Input Threshold Low	V <sub>CC</sub> = 3.3V		25	0.6	1.2	-	V
	V <sub>CC</sub> = 5.0V		25	0.8	1.5	-	V
Input Threshold High	V <sub>CC</sub> = 3.3V		25	-	1.5	2.4	V
	V <sub>CC</sub> = 5.0V		25	-	1.8	2.4	V
Input Hysteresis			25	-	0.5	-	V
Input Resistance			25	3	5	7	kΩ
Transmitter Outputs			•	•			
Output Voltage Swing	All transmitter outputs loaded w	ith 3kΩ to ground	Full	±5.0	±5.4	-	V
Output Resistance	V <sub>CC</sub> = V+ = V- = 0V, transmitter	output = ±2V	Full	300	10M	-	Ω
Output Short-Circuit Current			Full	-	±35	±60	mA
Output Leakage Current	V <sub>OUT</sub> = ±12V, V <sub>CC</sub> = 0V or 3V to 5.5V, automatic powerdown or FORCEOFF = GND		Full	-	-	±25	μA
Enhanced Automatic Powerdow	n (FORCEON = GND, FORCEO	FF = V <sub>CC</sub> )	•	•		•	
Receiver Input Thresholds to INVALID High	See Figure 13		Full	-2.7	-	2.7	V
Receiver Input Thresholds to INVALID Low	See Figure 13		Full	-0.3	-	0.3	V
INVALID, READY Output Voltage Low	I <sub>OUT</sub> = 1.6mA		Full	-	-	0.4	V
INVALID, READY Output Voltage High	I <sub>OUT</sub> = -1.0mA		Full	V <sub>CC</sub> -0.6	-	-	V
Receiver Positive or Negative ICL3238		25	-	0.1	-	μs	
Threshold to INVALID High Delay (t <sub>INVH</sub> )	All Others		25	-	1	-	μs
Receiver Positive or Negative	ICL3238		25	-	50	-	μs
Threshold to INVALID Low Delay (t <sub>INVL</sub> )	All Others		25	-	30	-	μs

Test conditions:  $V_{CC}$  = 3V to 5.5V,  $C_1$  -  $C_4$  = 0.1 $\mu$ F (ICL3238:  $C_1$  -  $C_4$  = 0.22 $\mu$ F at VCC = 3V); unless otherwise specified. Typical values are at TA = 25°C (Continued)

Parameter	Test Condit	ions	Temp (°C)	Min	Тур	Max	Unit
Receiver or Transmitter Edge to	ICL3238, Note 7		25	-	25	-	μs
Transmitters Enabled Delay (t <sub>WU</sub> )	All Others, Note 7		25	-	100	-	μs
Receiver or Transmitter Edge to Transmitters Disabled Delay (tautopwdn)	Note 7		Full	15	30	60	sec
Timing Characteristics							
Maximum Data Rate	$R_L$ = 3kΩ, CL = 1000pF, one tran	smitter switching	Full	250	500	-	kbps
Receiver Propagation Delay	Receiver input to receiver	t <sub>PHL</sub>	25	-	0.15	-	μs
	output, C <sub>L</sub> = 150pF	t <sub>PLH</sub>	25	-	0.15	-	μs
Receiver Output Enable Time	Normal operation (ICL3238 Only	Normal operation (ICL3238 Only)		-	200	-	ns
Receiver Output Disable Time	Normal operation (ICL3238 Only	Normal operation (ICL3238 Only)		-	200	-	ns
Transmitter Skew	t <sub>PHL</sub> - t <sub>PLH</sub>		25	-	100	-	ns
Receiver Skew	t <sub>PHL</sub> - t <sub>PLH</sub>		25	-	50	-	ns
Transition Region Slew Rate	V <sub>CC</sub> = 3.3V,	C <sub>L</sub> = 150pF to 1000pF	25	6	-	30	V/µs
	$R_L = 3k\Omega$ to $7k\Omega,$ Measured From 3V to -3V or -3V to 3V	C <sub>L</sub> = 150pF to 2500pF	25	4	8	30	V/µs
ESD Performance					•	•	
RS-232 Pins (T <sub>OUT</sub> , R <sub>IN</sub> )	Human Body Model		25	-	±15	-	kV
	IEC61000-4-2 Contact Discharge		25	-	±8	-	kV
	IEC61000-4-2 Air Gap Discharge		25	-	±10	-	kV
All Other Pins	Human Body Model		25	-	±2.5	-	kV

Note:

<sup>7.</sup> An "edge" is defined as a transition through the transmitter or receiver input thresholds.

# 3. Typical Performance Curves

 $V_{CC} = 3.3V, T_A = 25^{\circ}C$ 

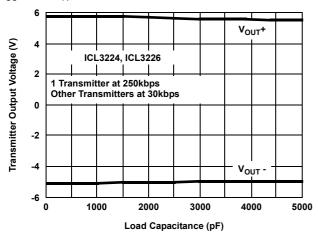


Figure 1. Transmitter Output Voltage vs Load Capacitance

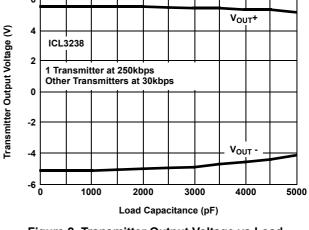


Figure 2. Transmitter Output Voltage vs Load Capacitance

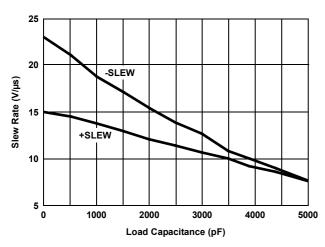


Figure 3. Slew Rate vs Load Capacitance

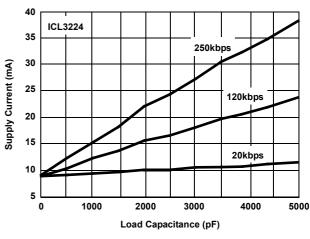


Figure 4. Supply Current vs Load Capacitance When Transmitting Data

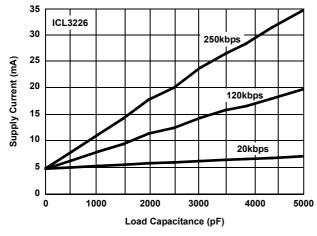


Figure 5. Supply Current vs Load Capacitance When Transmitting Data

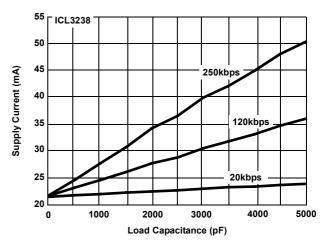


Figure 6. Supply Current vs Load Capacitance When Transmitting Data

 $V_{CC}$  = 3.3V,  $T_A$  = 25°C (Continued)

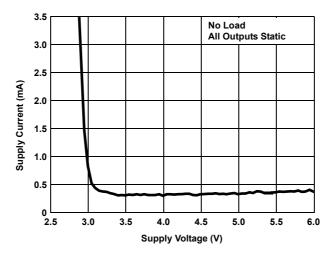


Figure 7. Supply Current vs Supply Voltage

## 4. Application Information

ICL3224, ICL3226, and ICL3238 (ISL32xx) devices operate from a single +3V to +5.5V supply, ensure a 250kbps minimum data rate, require only four small external  $0.1\mu F$  capacitors, feature low power consumption, and meet all EIA RS-232C and V.28 specifications.

### 4.1 Charge-Pump

The ICL32xx devices use regulated on-chip dual charge pumps as voltage doublers, and voltage inverters to generate  $\pm 5.5$ V transmitter supplies from a V<sub>CC</sub> supply as low as 3.0V, which allows them to maintain RS-232 compliant output levels over the  $\pm 10\%$  tolerance range of 3.3V powered systems. The efficient on-chip power supplies require only four small, external  $0.1\mu$ F capacitors for the voltage doubler and inverter functions at V<sub>CC</sub> = 3.3V. See the <u>Capacitor Selection</u> section, and <u>Table 6 on page 19</u> for capacitor recommendations for other operating conditions. The charge pumps operate discontinuously (turning off when the V+ and V- supplies are pumped up to the nominal values), resulting in significant power savings.

## 4.1.1 Charge Pump Absolute Maximum Ratings

These 3V to 5V RS-232 transceivers have been fully characterized for 3.0V to 3.6V operation, and at critical points for 4.5V to 5.5V operation. Furthermore, load conditions were favorable using static logic states only.

The specified maximum values for V+ and V- are +7V and -7V, respectively. These limits apply for VCC values set to 3.0V and 3.6V (see <u>Table 2</u>). For VCC values set to 4.5V and 5.5V, the maximum values for V+ and V- can approach +9V and -7V respectively (see <u>Table 3</u>). The breakdown characteristics for V+ and V- were measured with ±13V.

Table 2.	V+ and V- Values for $V_{CC} = 3$ .	.0V to 3.6V
----------	-------------------------------------	-------------

			T1 <sub>IN</sub>	V+	(V)	V- (V)	
C <sub>1</sub> (µF)	C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub> (μF)	Load	(Logic State)	V <sub>CC</sub> = 3.0V	V <sub>CC</sub> = 3.6V	V <sub>CC</sub> = 3.0V	V <sub>CC</sub> = 3.6V
0.1	0.1	Open	Н	5.8	6.56	-5.6	-5.88
			L	5.8	6.56	-5.6	-5.88
			2.4kbps	5.8	6.56	-5.6	-5.88
		3kΩ // 1000pF	Н	5.88	6.6	-5.56	-5.92
			L	5.76	6.36	-5.56	-5.76
			2.4kbps	6	6.64	-5.64	-5.96
0.047	0.33	Open	Н	5.68	6	-5.6	-5.6
			L	5.68	6	-5.6	-5.6
			2.4kbps	5.68	6	-5.6	-5.6
		3kΩ // 1000pF	Н	5.76	6.08	-5.64	-5.64
			L	5.68	6.04	-5.6	-5.6
			2.4kbps	5.84	6.16	-5.64	-5.72
1	1	Open	Н	5.88	6.24	-5.6	-5.6
			L	5.88	6.28	-5.6	-5.64
			2.4kbps	5.8	6.2	-5.6	-5.6
		3kΩ // 1000pF	Н	5.88	6.44	-5.64	-5.72
			L	5.88	6.04	-5.64	-5.64
			2.4kbps	5.92	6.4	-5.64	-5.64

Table 3. V+ and V- Values for  $V_{CC}$  = 4.5V to 5.5V

			T1 <sub>IN</sub> (Logic	V+	(V)	V- (V)	
C <sub>1</sub> (μF)	C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub> (μF)	Load	State)	V <sub>CC</sub> = 4.5V	V <sub>CC</sub> = 5.5V	V <sub>CC</sub> = 4.5V	V <sub>CC</sub> = 5.5V
0.1	0.1	Open	Н	7.44	8.48	-6.16	-6.4
			L	7.44	8.48	-6.16	-6.44
			2.4kbps	7.44	8.48	-6.17	-6.44
		3kΩ // 1000pF	Н	7.76	8.88	-6.36	-6.72
			L	7.08	8	-5.76	-5.76
			2.4kbps	7.76	8.84	-6.4	-6.64
0.047	0.33	Open	Н	6.44	6.88	-5.8	-5.88
			L	6.48	6.88	-5.84	-5.88
			2.4kbps	6.44	6.88	-5.8	-5.88
		3kΩ // 1000pF	Н	6.64	7.28	-5.92	-6.04
			L	6.24	6.6	-5.52	-5.52
			2.4kbps	6.72	7.16	-5.92	-5.96
1	1	Open	Н	6.84	7.6	-5.76	-5.76
			L	6.88	7.6	-5.76	-5.76
			2.4kbps	6.92	7.56	-5.72	-5.76
		3kΩ // 1000pF	Н	7.28	8.16	-5.8	-5.92
			L	6.44	6.84	-5.64	-6.84
			2.4kbps	7.08	7.76	-5.8	-5.8

The resulting new maximum voltages at V+ and V- are listed in Table 4.

Table 4. New Measured Withstanding Voltages

V+, V- to Ground	±13V
V+ to V-	20V

### 4.2 Transmitters

The transmitters are proprietary, low dropout, inverting drivers that translate TTL/CMOS inputs to EIA/TIA-232 output levels. The transmitters are coupled with the on-chip ±5.5V supplies to deliver true RS-232 levels over a wide range of single supply system voltages.

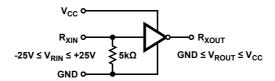
Transmitter outputs disable and assume a high impedance state when the device enters the powerdown mode (see <u>Table 5 on page 15</u>). The outputs can be driven to ±12V when disabled.

All devices ensure a 250kbps data rate for full load conditions ( $3k\Omega$  and 1000pF),  $V_{CC} \ge 3.0V$ , with one transmitter operating at full speed. Under more typical conditions of  $V_{CC} \ge 3.3V$ ,  $R_L = 3k\Omega$ , and  $C_L = 250pF$ , one transmitter easily operates at 1Mbps.

Transmitter inputs float if left unconnected, and can increase  $I_{CC}$ . Connect unused inputs to GND for best performance.

#### 4.3 Receivers

All the ICL32xx devices contain standard inverting receivers, but only the ICL3238 receiver can tri-state, using the FORCEOFF control line. The ICL3238 includes a noninverting (monitor) receiver (denoted by the  $R_{OUTB}$  label) that is always active, regardless of the state of any control lines. This receiver converts RS-232 signals to CMOS output levels and accepts inputs up to  $\pm 25V$  while presenting the required  $3k\Omega$  to  $7k\Omega$  input impedance (see Figure 8) even if the power is off ( $V_{CC}$  = 0V). The receivers' Schmitt trigger input stage uses hysteresis to increase noise immunity and decrease errors due to slow input signal transitions.



**Figure 8. Inverting Receiver Connections** 

The ICL3238 inverting receiver disables during forced (manual) powerdown, but not during automatic powerdown (see <u>Table 5 on page 15</u>). Conversely, the monitor receiver remains active even during manual powerdown, which makes it extremely useful for Ring Indicator monitoring. Standard receivers driving powered down peripherals must be disabled to prevent current flow through the peripheral's protection diodes (see <u>Figures 9</u> and <u>10</u>). When powered down, they cannot be used for wake up functions, but the corresponding monitor receiver can be dedicated to this task as shown in <u>Figure 10</u>.

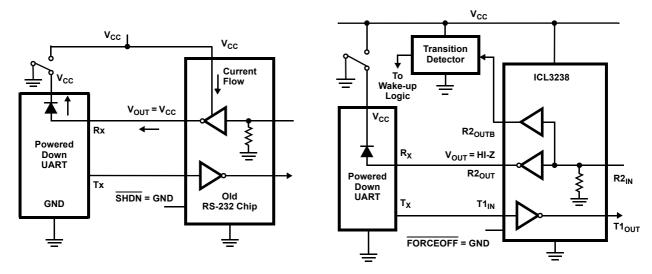


Figure 9. Power Drain Through Powered Down Peripheral

Figure 10. Disabled Receivers Prevent Power Drain

## 4.4 Powerdown Functionality

The 3V ICL32xx devices require a nominal supply current of 0.3mA during normal operation (not in powerdown mode). This current is considerably less than the 5mA to 11mA current required of 5V RS-232 devices. The already low current requirement drops significantly when the device enters powerdown mode. In powerdown, supply current drops to 1 $\mu$ A, because the on-chip charge pump turns off (V+ collapses to V<sub>CC</sub>, V- collapses to GND), and the transmitter outputs tri-state. Inverting receiver outputs may disable in powerdown; see <u>Table 5</u> for details. This micro-power mode makes these devices ideal for battery powered and portable applications.

Table 5. Powerdown Logic Truth Table

	OWEIGOW								
RCVR or XMTR Edge Within 30 Sec?	FORCEOFF Input	FORCEON Input	Transmitter Outputs	Receiver Outputs	(Note 8) ROUTB Outputs	RS-232 Level Present at Receiver Input?	INVALID Output	Mode of Operation	
ICL3224, ICL3226									
No	Н	Н	Active	Active	N.A.	No	L	Normal Operation (Enhanced	
No	Н	Н	Active	Active	N.A.	Yes	Н	Auto Powerdown Disabled)	
Yes	Н	L	Active	Active	N.A.	No	L	Normal Operation (Enhanced	
Yes	Н	L	Active	Active	N.A.	Yes	Н	Auto Powerdown Enabled)	
No	Н	L	High-Z	Active	N.A.	No	L	Powerdown Due to Enhanced	
No	Н	L	High-Z	Active	N.A.	Yes	Н	Auto Powerdown Logic	
Х	L	Х	High-Z	Active	N.A.	No	L	Manual Powerdown	
Х	L	Х	High-Z	Active	N.A.	Yes	Н		
ICL322X - IN	VALID DRIVI	NG FORCEO	N AND FORCE	OFF (Emula	tes Automa	tic Powerdow	n)		
Х	Note 9	Note 9	Active	Active	N.A.	Yes	Н	Normal Operation	
Х	Note 9	Note 9	High-Z	Active	N.A.	No	L	Forced Auto Powerdown	
ICL3238									
No	Н	Н	Active	Active	Active	No	L	Normal Operation (Enhanced	
No	Н	Н	Active	Active	Active	Yes	Н	Auto Powerdown Disabled)	
Yes	Н	L	Active	Active	Active	No	L	Normal Operation (Enhanced	
Yes	Н	L	Active	Active	Active	Yes	Н	Auto Powerdown Enabled)	
No	Н	L	High-Z	Active	Active	No	L	Powerdown Due to Enhanced	
No	Н	L	High-Z	Active	Active	Yes	Н	Auto Powerdown Logic	
Х	L	Х	High-Z	High-Z	Active	No	L	Manual Powerdown	
Х	L	Х	High-Z	High-Z	Active	Yes	Н		
ICL3238 - IN	VALID DRIVIN	IG FORCEON	AND FORCE	OFF (Emulat	es Automat	tic Powerdow	n)		
Х	Note 9	Note 9	Active	Active	Active	Yes	Н	Normal Operation	
Х	Note 9	Note 9	High-Z	High-Z	Active	No	L	Forced Auto Powerdown	
Nata.									

#### Notes:

<sup>8.</sup> Applies only to the ICL3238.

<sup>9.</sup> Input is connected to INVALID Output.

## 4.4.1 Software Controlled (Manual) Powerdown

The ICL32xx devices allow you to force the IC into the low power, standby state, and use a two pin approach where the FORCEON and FORCEOFF inputs determine the IC's mode. For always enabled operation, FORCEON and FORCEOFF are both strapped high. Under logic or software control, only the FORCEOFF input needs to be driven to switch between active and powerdown modes. The FORCEON state is not critical because FORCEOFF overrides FORCEON. However, if strictly manual control over powerdown is needed, you must strap FORCEON high to disable the automatic powerdown circuitry. The ICL3238's inverting (standard) receiver outputs also disables when the device is in powerdown and eliminates the possible current path through a shutdown peripheral's input protection diode (see Figures 9 and 10).

Connecting FORCEOFF and FORCEON together disables the enhanced automatic powerdown feature, which enables them to function as a manual SHUTDOWN input (see Figure 11).

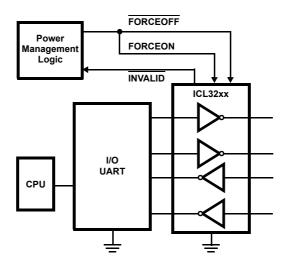


Figure 11. Connections for Manual Powerdown When No Valid Receiver Signals are Present

With any of the above control schemes, the time required to exit powerdown, and resume transmission is only 100µs.

When using both manual and enhanced automatic powerdown (FORCEON = 0), the ICL32xx devices do not power up from manual powerdown until both FORCEOFF and FORCEON are driven high, or until a transition occurs on a receiver or transmitter input. Figure 12 shows a circuit for ensuring that the ICL32xx powers up as soon as FORCEOFF switches high. The rising edge of the master powerdown signal forces the device to power up, and the ICL32xx returns to enhanced automatic powerdown mode an RC time constant after this rising edge. The time constant is not critical, because the ICL32xx remains powered up for 30s after the FORCEON falling edge, even if there are no signal transitions. The delay gives slow-to-wake systems (such as a mouse) plenty of time to start transmitting, and as long as it starts transmitting within 30s, both systems remain enabled.

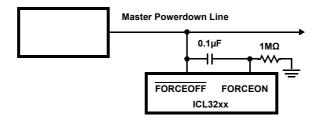


Figure 12. Circuit to Ensure Immediate Power Up When Exiting Forced Powerdown

## 4.4.2 INVALID Output

Table 5 on page 15 shows that the INVALID output always indicates whether or not 30μs have elapsed with invalid RS-232 signals (see Figures 13 and 15) persisting on all of the receiver inputs and provides you a way to determine when the interface block should power down. Invalid receiver levels occur whenever the driving peripheral's outputs are shut off (powered down) or when the RS-232 interface cable is disconnected. If an interface cable is disconnected and all the receiver inputs are floating (but pulled to GND by the internal receiver pull down resistors), the INVALID logic detects the invalid levels and drives the output low. The power management logic then uses this indicator to power down the interface block. Reconnecting the cable restores valid levels at the receiver inputs, INVALID switches high, and the power management logic wakes up the interface block. INVALID can also be used to indicate the DTR or Ring Indicator signal, as long as the other receiver inputs are floating, or driven to GND (as in the case of a powered down driver).

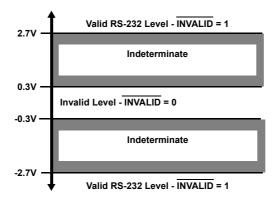


Figure 13. Definition of Valid RS-232 Receiver Levels

#### 4.5 Enhanced Automatic Powerdown

Even greater power savings are available by using the ICL32xx's enhanced automatic powerdown function. When the enhanced powerdown logic determines that no transitions have occurred on any of the transmitter nor receiver inputs for 30s, the charge pump and transmitters powerdown, thereby reducing supply current to  $1\mu A$ . The ICL32xx devices automatically power back up whenever they detect a transition on one of these inputs. The automatic powerdown feature provides additional system power savings without changes to the existing operating system.

Enhanced automatic powerdown operates when the FORCEON input is low, and the FORCEOFF input is high. Tying FORCEON high disables automatic powerdown, but manual powerdown is always available using the overriding FORCEOFF input. Table 5 summarizes the enhanced automatic powerdown functionality.

<u>Figure 14</u> shows the enhanced powerdown control logic. **Note:** When the ICL32xx enters powerdown (manually or automatically), the 30-second timer remains timed out (set), keeping the ICL32xx powered down until FORCEON transitions high, or until a transition occurs on a receiver or transmitter input.

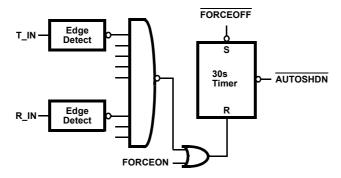


Figure 14. Enhanced Automatic Powerdown Logic

The INVALID output signal switches low to indicate that invalid levels have persisted on all of the receiver inputs for more than 30µs (see Figure 15), but this signal switch has no direct effect on the state of the ICL32xx (see the next sections for methods of using INVALID to power down the device). INVALID switches high 1µs after detecting a valid RS-232 level on a receiver input. INVALID operates in all modes (forced or automatic powerdown, or forced on), so it is also useful for systems employing manual powerdown circuitry.

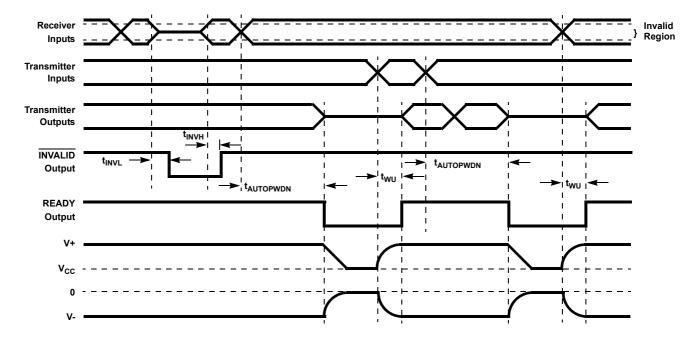


Figure 15. Enhanced Automatic Powerdown, INVALID and READY Timing Diagrams

The time to recover from automatic powerdown mode is typically 100µs.

### 4.5.1 Emulating Standard Automatic Powerdown

If enhanced automatic powerdown is not desired, you can implement the standard automatic powerdown feature (mimics the function on the ICL3221/23/43) by connecting the INVALID output to the FORCEON and FORCEOFF inputs, as shown in Figure 16. After 30µs of invalid receiver levels, INVALID switches low and drives the ICL32xx into a forced powerdown condition. INVALID switches high as soon as a receiver input senses a valid RS-232 level, forcing the ICL32xx to power on. See the "INVALID Driving FORCEON and FORCEOFF" sections of Table 5 on page 15 for an operational summary. This operational mode is perfect for hand-held devices that communicate with another computer using a detachable cable. Detaching the cable allows the internal receiver pull-down resistors to pull the inputs to GND (an invalid RS-232 level), causing the 30µs timer to time-out and drive the IC into powerdown. Reconnecting the cable restores valid levels, causing the IC to power back up.

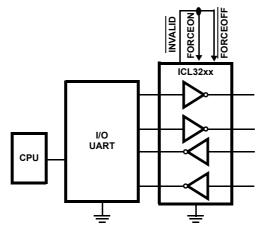


Figure 16. Connections for Automatic Powerdown When No Valid Receiver Signals are Present

## 4.5.2 Hybrid Automatic Powerdown Options

For devices that communicate only through a detachable cable, you can connect INVALID to FORCEOFF (with FORCEON = 0). While the cable is attached, INVALID and FORCEOFF remain high, so the enhanced automatic powerdown logic powers down the RS-232 device whenever there is 30s of inactivity on the receiver and transmitter inputs. Detaching the cable allows the receiver inputs to drop to an invalid level (GND), so INVALID switches low and forces the RS-232 device to power down. The ICL32xx remains powered down until the cable is reconnected (INVALID = FORCEOFF = 1), and a transition occurs on a receiver or transmitter input (see Figure 14 on page 17). For immediate power up when the cable is reattached, connect FORCEON to FORCEOFF through a network similar to that shown in Figure 12 on page 16.

### 4.6 READY Output (ICL3224 and ICL3226 only)

The READY output indicates that the ICL322x devices are ready to transmit. READY switches low whenever the device enters powerdown, and switches back high during power-up when V- reaches -4V or lower.

## 4.7 Capacitor Selection

The charge pumps require  $0.1\mu F$  capacitors for 3.3V operation. For other supply voltages see <u>Table 6</u> for capacitor values. Do not use values smaller than those listed in <u>Table 6</u>. Increasing the capacitor values (by a factor of 2) reduces ripple on the transmitter outputs and slightly reduces power consumption.  $C_2$ ,  $C_3$ , and  $C_4$  can be increased without increasing  $C_1$ 's value, however, do not increase  $C_1$  without also increasing  $C_2$ ,  $C_3$ , and  $C_4$  to maintain the proper ratios ( $C_1$  to the other capacitors).

When using minimum required capacitor values, make sure that capacitor values do not degrade excessively with temperature. If in doubt, use capacitors with a larger nominal value. The capacitor's equivalent series resistance (ESR) usually rises at low temperatures and influences the amount of ripple on V+ and V-.

Table 6. Required Capacitor Values

V <sub>CC</sub> (V)	C <sub>1</sub> (μF)	C <sub>2</sub> , C <sub>3</sub> , C <sub>4</sub> (μF)
3.0 to 3.6 (3.3V ±10%)	0.1 (0.22)	0.1 (0.22)
3.15 to 3.6 (3.3V ±5%)	(0.1)	(0.1)
4.5 to 5.5	0.047	0.33
3.0 to 5.5	0.1 (0.22)	0.47 (1.0)

Note:

#### 4.8 Power Supply Decoupling

In most circumstances a  $0.1\mu F$  bypass capacitor is adequate. In applications that are particularly sensitive to power supply noise, decouple  $V_{CC}$  to ground with a capacitor of the same value as the charge-pump capacitor  $C_1$ . Connect the bypass capacitor as close as possible to the IC.

<sup>10.</sup> Parenthesized values apply only to the ICL3238

## 4.9 Transmitter Outputs when Exiting Powerdown

Figure 17 shows the response of two transmitter outputs when exiting powerdown mode. As they activate, the two transmitter outputs properly go to opposite RS-232 levels, with no glitching, ringing, nor undesirable transients. Each transmitter is loaded with  $3k\Omega$  in parallel with 2500pF. **Note**: The transmitters enable only when the magnitude of the supplies exceed approximately 3V.

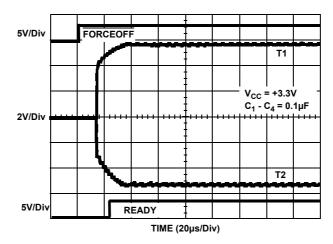


Figure 17. Transmitter Outputs When Exiting Powerdown

#### 4.10 Operation Down to 2.7V

The ICL32xx transmitter outputs meet RS-562 levels ( $\pm 3.7V$ ), at the full data rate, with  $V_{CC}$  as low as 2.7V. RS-562 levels typically ensure interoperability with RS-232 devices.

## 4.11 High Data Rates

The ICL32xx maintain the RS-232 ±5V minimum transmitter output voltages even at high data rates. Figure 18 shows a transmitter loopback test circuit, and Figure 19 on page 21 shows the loopback test result at 120kbps. For this test, all transmitters were simultaneously driving RS-232 loads in parallel with 1000pF, at 120kbps. Figure 20 on page 21 shows the loopback results for a single transmitter driving 1000pF and an RS-232 load at 250kbps. The static transmitters were also loaded with an RS-232 receiver.

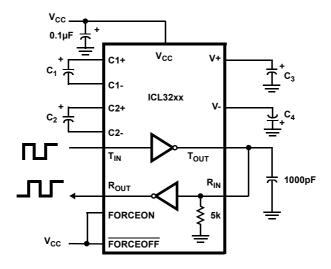
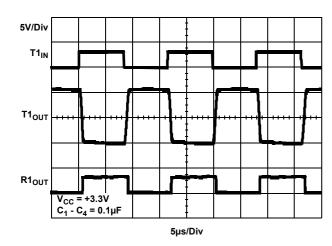


Figure 18. Transmitter Loopback Test Circuit



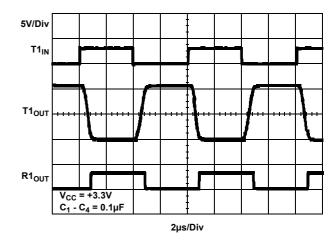


Figure 19. Loopback Test at 120kbps

Figure 20. Loopback Test at 250kbps

## 4.12 Interconnection with 3V and 5V Logic

The ICL32xx directly interface with 5V CMOS and TTL logic families. The AC, HC, and CD4000 outputs can drive ICL32xx inputs with the ICL32xx at 3.3V and the logic supply at 5V, but ICL32xx outputs do not reach the minimum  $V_{IH}$  for these logic families. See <u>Table 7</u> for more information.

Table 7. Logic Family Compatibility with Various Supply Voltages

System Power Supply Voltage (V)	V <sub>CC</sub> Supply Voltage (V)	Compatibility
3.3	3.3	Compatible with all CMOS families.
5	5	Compatible with all TTL and CMOS logic families.
5	3.3	Compatible with ACT and HCT CMOS, and with TTL. ICL32xx outputs are incompatible with AC, HC, and CD4000 CMOS inputs.

# 5. Die Characteristics

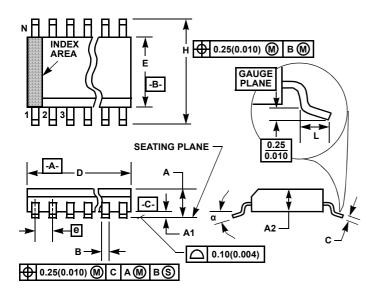
Substrate Potential (Powered Up)	GND
Transistor Count	ICL3224: 937 ICL3226: 825 ICL3238: 1235
Process	Si Gate CMOS

# 6. Revision History

Description
It to latest formatting. It Related Literature section. Id Related Literature section. Id ICL3244 and MAX3244 information from document. If Ordering information table by adding tape and reel information, updated notes, removed retired parts, mped EOL parts. In Charge Pump Absolute Maximum Ratings" on page 12. In Revision History

# 7. Package Outline Drawings

For the most recent package outline drawing, see M16.209.



# M16.209 (JEDEC MO-150-AC ISSUE B) 16 Lead Shrink Small Outline Plastic Package (SSOP

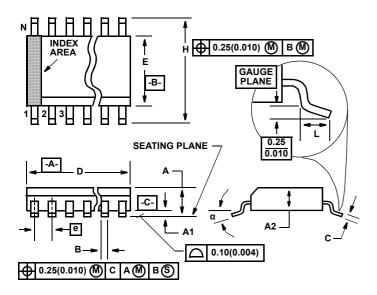
	INCHES		MILLIM		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α	-	0.078	-	2.00	-
A1	0.002	-	0.05	-	-
A2	0.065	0.072	1.65	1.85	-
В	0.009	0.014	0.22	0.38	9
С	0.004	0.009	0.09	0.25	-
D	0.233	0.255	5.90	6.50	3
Е	0.197	0.220	5.00	5.60	4
е	0.026	BSC	0.65 BSC		-
Н	0.292	0.322	7.40	8.20	-
L	0.022	0.037	0.55	0.95	6
N	16		1	6	7
α	0°	8°	0°	8°	-

Rev. 3 6/05

#### Notes:

- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs.
   Mold flash, protrusion and gate burrs shall not exceed 0.20mm (0.0078 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.20mm (0.0078 inch) per side.
- The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- Dimension "B" does not include dambar protrusion. Allowable dambar protrusion shall be 0.13mm (0.005 inch) total in excess of "B" dimension at maximum material condition.
- 10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

For the most recent package outline drawing, see M20.209.



#### Notes:

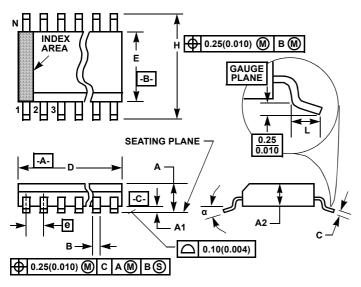
- 1. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.20mm (0.0078 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.20mm (0.0078 inch) per side.
- 5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
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- 8. Terminal numbers are shown for reference only.
- Dimension "B" does not include dambar protrusion. Allowable dambar protrusion shall be 0.13mm (0.005 inch) total in excess of "B" dimension at maximum material condition.
- 10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M20.209 (JEDEC MO-150-AE ISSUE B) 20 Lead Shrink Small Outline Plastic Package (SSOP)

20 2044 01111111 0111411 04411110 1 140114 1 40114 90 (0001)								
	INC	HES	MILLIM	ETERS				
SYMBOL	MIN	MAX	MIN	MAX	NOTES			
Α	0.068	0.078	1.73	1.99				
A1	0.002	0.008'	0.05	0.21				
A2	0.066	0.070'	1.68	1.78				
В	0.010'	0.015	0.25	0.38	9			
С	0.004	0.008	0.09	0.20'				
D	0.278	0.289	7.07	7.33	3			
Е	0.205	0.212	5.20'	5.38	4			
е	0.026	BSC	0.65	BSC				
Н	0.301	0.311	7.65	7.90'				
L	0.025	0.037	0.63	0.95	6			
N	20		2	0	7			
α	0 deg.	8 deg.	0 deg.	8 deg.				

Rev. 3 11/02

For the most recent package outline drawing, see M28.209.



#### Notes:

- Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication Number 95.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
- Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.20mm (0.0078 inch) per side.
- Dimension "E" does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.20mm (0.0078 inch) per side.
- 5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- Dimension "B" does not include dambar protrusion. Allowable dambar protrusion shall be 0.13mm (0.005 inch) total in excess of "B" dimension at maximum material condition.
- 10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M28.209 (JEDEC MO-150-AH ISSUE B) 28 Lead Shrink Small Outline Plastic Package (SSOP)

	INCHES		MILLIM		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α	-	0.078	-	2.00	-
A1	0.002	-	0.05	-	-
A2	0.065	0.072	1.65	1.85	-
В	0.009	0.014	0.22	0.38	9
С	0.004	0.009	0.09	0.25	-
D	0.390	0.413	9.90	10.50	3
Е	0.197	0.220	5.00	5.60	4
е	0.026	BSC	0.65	BSC	-
Н	0.292	0.322	7.40	8.20	-
L	0.022	0.037	0.55	0.95	6
N	28		2	8	7
α	0°	8°	0°	8°	-

Rev. 2 6/05

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